

T-46-09-05

8-Bit Serial-Input/Parallel-Output Shift Register

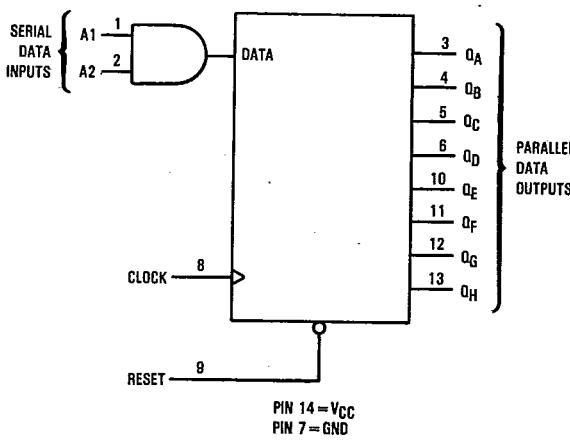
High-Performance Silicon-Gate CMOS

The MC54/74HC164 is identical in pinout to the LS164. The device inputs are compatible with standard CMOS outputs; with pullup resistors, they are compatible with LSTTL outputs.

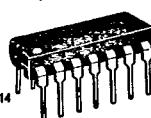
The MC54/74HC164 is an 8-bit, serial-input to parallel-output shift register. Two serial data inputs, A1 and A2, are provided so that one input may be used as a data enable. Data is entered on each rising edge of the clock. The active-low asynchronous Reset overrides the Clock and Serial Data inputs.

- Output Drive Capability: 10 LSTTL Loads
- Outputs Directly Interface to CMOS, NMOS, and TTL
- Operating Voltage Range: 2 to 6 V
- Low Input Current: 1 μ A
- High Noise Immunity Characteristic of CMOS Devices
- In Compliance with the Requirements Defined by JEDEC Standard No. 7A
- Chip Complexity: 244 FETs or 61 Equivalent Gates

LOGIC DIAGRAM



MC54/74HC164

J SUFFIX
CERAMIC
CASE 632-08N SUFFIX
PLASTIC
CASE 646-06D SUFFIX
SOIC
CASE 751A-02

ORDERING INFORMATION

MC74HCXXXN	Plastic
MC54HCXXXJ	Ceramic
MC74HCXXXD	SOIC

$T_A = -55^\circ$ to 125°C for all packages.
Dimensions in Chapter 7.

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PIN ASSIGNMENT

A1	1	•	14	V _{CC}
A2	2		13	Q _H
QA	3		12	Q _G
QB	4		11	Q _F
QC	5		10	Q _E
QE	6		9	RESET
GND	7		8	CLOCK

FUNCTION TABLE

Reset	Clock	A1 A2	Inputs				Outputs			
			QA	QB	...	QH				
L	X	X X	L	L	...	L				
H	—	X X					no change			
H	—	H D	D	Q _{An}	...	Q _{Gn}				
H	—	D H	D	Q _{An}	...	Q _{Gn}				

D = data input

Q_{An} - Q_{Gn} = data shifted from the previous stage on a rising edge at the clock input.

MAXIMUM RATINGS*

Symbol	Parameter	Value	Unit
V _{CC}	DC Supply Voltage (Referenced to GND)	-0.5 to +7.0	V
V _{in}	DC Input Voltage (Referenced to GND)	-1.5 to V _{CC} +1.5	V
V _{out}	DC Output Voltage (Referenced to GND)	-0.5 to V _{CC} +0.5	V
I _{in}	DC Input Current, per Pin	±20	mA
I _{out}	DC Output Current, per Pin	±25	mA
I _{CC}	DC Supply Current, V _{CC} and GND Pins	±50	mA
P _D	Power Dissipation in Still Air, Plastic or Ceramic DIP† SOIC Package	750 500	mW
T _{stg}	Storage Temperature	-65 to +150	°C
T _L	Lead Temperature, 1 mm from Case for 10 Seconds (Plastic DIP or SOIC Package) (Ceramic DIP)	260 300	°C

This device contains protection circuitry to guard against damage due to high static voltages or electric fields. However, precautions must be taken to avoid applications of any voltage higher than maximum rated voltages to this high-impedance circuit. For proper operation, V_{in} and V_{out} should be constrained to the range GND ≤(V_{in} or V_{out})≤V_{CC}. Unused inputs must always be tied to an appropriate logic voltage level (e.g., either GND or V_{CC}). Unused outputs must be left open.

*Maximum Ratings are those values beyond which damage to the device may occur.

Functional operation should be restricted to the Recommended Operating Conditions.

†Derating — Plastic DIP: -10 mW/°C from 65° to 125°C

Ceramic DIP: -10 mW/°C from 100° to 125°C

SOIC Package: -7 mW/°C from 65° to 125°C

For high frequency or heavy load considerations, see Chapter 4.

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter	Min	Max	Unit	
V _{CC}	DC Supply Voltage (Referenced to GND)	2.0	6.0	V	
V _{in} , V _{out}	DC Input Voltage, Output Voltage (Referenced to GND)	0	V _{CC}	V	
T _A	Operating Temperature, All Package Types	-55	+125	°C	
t _r , t _f	Input Rise and Fall Time (Figure 1)	V _{CC} =2.0 V V _{CC} =4.5 V V _{CC} =6.0 V	0 0 0	1000 500 400	ns

DC ELECTRICAL CHARACTERISTICS (Voltages Referenced to GND)

Symbol	Parameter	Test Conditions	V _{CC} V	Guaranteed Limit			Unit
				25°C to -55°C	≤85°C	≤125°C	
V _{IH}	Minimum High-Level Input Voltage	V _{out} =0.1 V or V _{CC} -0.1 V I _{out} ≤20 μA	2.0 4.5 6.0	1.5 3.15 4.2	1.5 3.15 4.2	1.5 3.15 4.2	V
V _{IL}	Maximum Low-Level Input Voltage	V _{out} =0.1 V or V _{CC} -0.1 V I _{out} ≤20 μA	2.0 4.5 6.0	0.3 0.9 1.2	0.3 0.9 1.2	0.3 0.9 1.2	V
V _{OH}	Minimum High-Level Output Voltage	V _{in} =V _{IH} or V _{IL} I _{out} ≤20 μA	2.0 4.5 6.0	1.9 4.4 5.9	1.9 4.4 5.9	1.9 4.4 5.9	V
		V _{in} =V _{IH} or V _{IL} I _{out} ≤4.0 mA I _{out} ≤5.2 mA	4.5 6.0	3.98 5.48	3.84 5.34	3.70 5.20	
V _{OL}	Maximum Low-Level Output Voltage	V _{in} =V _{IH} or V _{IL} I _{out} ≤20 μA	2.0 4.5 6.0	0.1 0.1 0.1	0.1 0.1 0.1	0.1 0.1 0.1	V
		V _{in} =V _{IH} or V _{IL} I _{out} ≤4.0 mA I _{out} ≤5.2 mA	4.5 6.0	0.26 0.26	0.33 0.33	0.40 0.40	
I _{in}	Maximum Input Leakage Current	V _{in} =V _{CC} or GND	6.0	±0.1	±1.0	±1.0	μA
I _{CC}	Maximum Quiescent Supply Current (per Package)	V _{in} =V _{CC} or GND I _{out} =0 μA	6.0	8	80	160	μA

NOTE: Information on typical parametric values can be found in Chapter 4.

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AC ELECTRICAL CHARACTERISTICS ($C_L = 50 \text{ pF}$, Input $t_r = t_f = 6 \text{ ns}$)

Symbol	Parameter	V_{CC} V	Guaranteed Limit			Unit
			25°C to -55°C	≤ 85°C	≤ 125°C	
f_{max}	Maximum Clock Frequency (50% Duty Cycle) (Figures 1 and 4)	2.0 4.5 6.0	6.0 30 35	4.8 24 28	4.0 20 24	MHz
$t_{PLH},$ t_{PHL}	Maximum Propagation Delay, Clock to Q (Figures 1 and 4)	2.0 4.5 6.0	175 35 30	220 44 37	265 63 45	ns
t_{PHL}	Maximum Propagation Delay, Reset to Q (Figures 2 and 4)	2.0 4.5 6.0	205 41 35	255 51 43	310 62 53	ns
$t_{TLH},$ t_{THL}	Maximum Output Transition Time, Any Output (Figures 1 and 4)	2.0 4.5 6.0	75 15 13	95 19 16	110 22 19	ns
C_{in}	Maximum Input Capacitance	—	10	10	10	pF

NOTES:

1. For propagation delays with loads other than 50 pF, see Chapter 4.
2. Information on typical parametric values can be found in Chapter 4.

CPD	Power Dissipation Capacitance (Per Package) Used to determine the no-load dynamic power consumption: $P_D = CPD V_{CC}^2 f + I_{CC} V_{CC}$ For load considerations, see Chapter 4.	Typical @ 25°C, $V_{CC} = 5.0 \text{ V}$		pF
		140		

TIMING REQUIREMENTS (Input $t_r = t_f = 6 \text{ ns}$)

Symbol	Parameter	V_{CC} V	Guaranteed Limit			Unit
			25°C to -55°C	≤ 85°C	≤ 125°C	
t_{SU}	Minimum Setup Time, A1 or A2 to Clock (Figure 3)	2.0 4.5 6.0	50 10 9	65 13 11	75 15 13	ns
t_h	Minimum Hold Time, Clock to A1 or A2 (Figure 3)	2.0 4.5 6.0	5 5 5	5 5 5	5 5 5	ns
t_{REC}	Minimum Recovery Time, Reset Inactive to Clock (Figure 2)	2.0 4.5 6.0	5 5 5	5 5 5	5 5 5	ns
t_w	Minimum Pulse Width, Clock (Figure 1)	2.0 4.5 6.0	80 16 14	100 20 17	120 24 20	ns
$t_{w'}$	Minimum Pulse Width, Reset (Figure 2)	2.0 4.5 6.0	80 16 14	100 20 17	120 24 20	ns
t_r, t_f	Maximum Input Rise and Fall Times (Figure 1)	2.0 4.5 6.0	1000 500 400	1000 500 400	1000 500 400	ns

NOTE: Information on typical parametric values can be found in Chapter 4.

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PIN DESCRIPTIONS

INPUTS

A1, A2 (PINS 1, 2) — Serial Data Inputs. Data at these inputs determine the data to be entered into the first stage of the shift register. For a high level to be entered into the shift register, both A1 and A2 inputs must be high, thereby allowing one input to be used as a data-enable input. When only one serial input is used, the other must be connected to V_{CC}.

CLOCK (PIN 8) — Shift Register Clock. A positive-going transition on this pin shifts the data at each stage to the next stage. The shift register is completely static, allowing clock rates down to DC in a continuous or intermittent mode.

OUTPUTS

Q_A — Q_H (PINS 3, 4, 5, 6, 10, 11, 12, 13) — Parallel Shift Register Outputs. The shifted data is presented at these outputs in true, or noninverted, form.

CONTROL INPUT

RESET (PIN 9) — Active-Low, Asynchronous Reset Input. A low voltage applied to this input resets all internal flip-flops and sets outputs Q_A — Q_H to the low level state.

SWITCHING WAVEFORMS

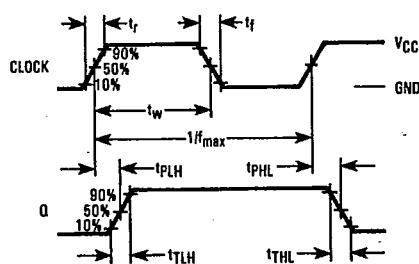


Figure 1

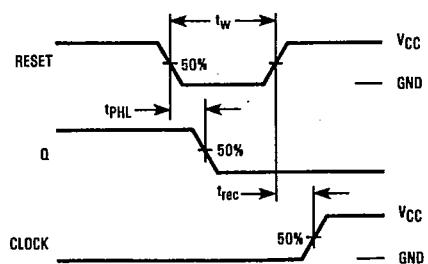
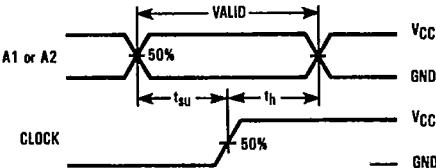
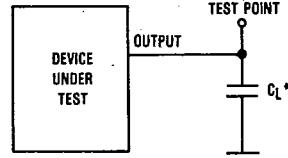


Figure 2



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Figure 3



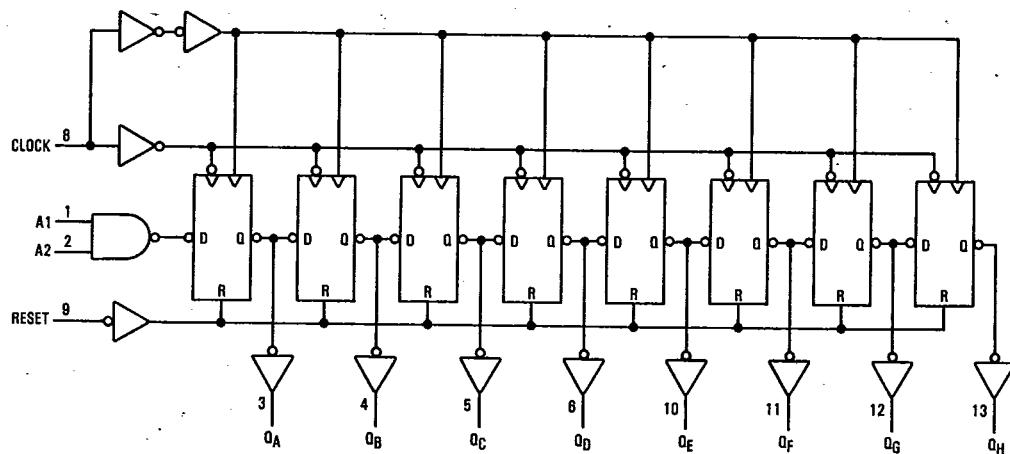
*Includes all probe and jig capacitance.

Figure 4. Test Circuit

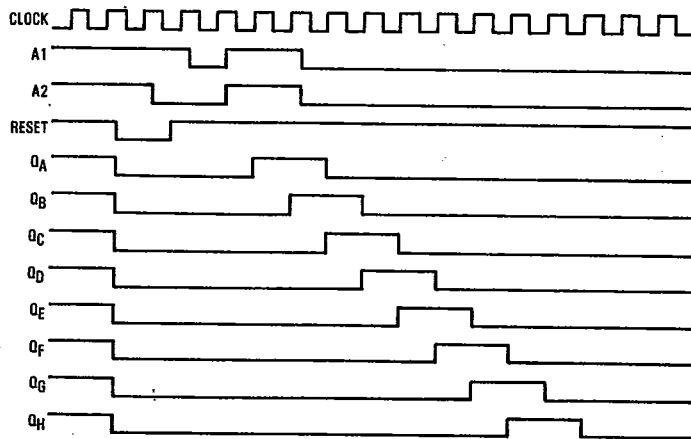
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EXPANDED LOGIC DIAGRAM



TIMING DIAGRAM



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